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April 2015

### **FDMC86262P**

# P-Channel PowerTrench® MOSFET

-150 V, -2 A, 307 m $\Omega$ 

#### **Features**

- Max  $r_{DS(on)}$  = 307 m $\Omega$  at  $V_{GS}$  = -10 V,  $I_D$  = -2 A
- Max  $r_{DS(on)}$  = 356 m $\Omega$  at  $V_{GS}$  = -6 V,  $I_D$  = -1.8 A
- Very Low r<sub>DS(on)</sub> Mid Voltage P-Channel Silicon Technology Optimised for Low Qg
- Optimised for Fast Switching Applications as well as Load Switch Applications
- 100% UIL Tested
- RoHS Compliant

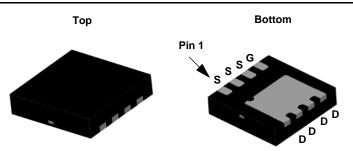


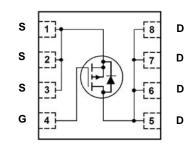
#### **General Description**

This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench technology. This very high density process is especially tailored to minimize onstate resistance and optimizad for superior switching performance.

#### **Applications**

- Active Clamp Switch
- Load Switch





MLP 3.3x3.3

#### **MOSFET Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Param	eter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage			-150	V
V <sub>GS</sub>	Gate to Source Voltage			±25	V
	Drain Current -Continuous	T <sub>C</sub> = 25°C	(Note 5)	-8.4	
	-Continuous	T <sub>C</sub> = 100°C	(Note 5)	-5.3	^
ID	-Continuous	$T_A = 25^{\circ}C$	(Note 1a)	-2	Α
	-Pulsed		(Note 4)	-35	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	37	mJ
D	Power Dissipation	T <sub>C</sub> = 25°C		40	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1a)	2.3	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a	53	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC86262P	FDMC86262P	Power 33	13"	12 mm	3000 units

### **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	acteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-150			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu A$ , referenced to 25°C		-86		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -120 V, V <sub>GS</sub> = 0 V			-1	μΑ
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### **On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-2	-2.9	-4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25°C		5		mV/°C
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = -10 \text{ V}, I_D = -2 \text{ A}$		241	307	
		$V_{GS} = -6 \text{ V}, I_D = -1.8 \text{ A}$		266	356	mΩ
		$V_{GS} = -10 \text{ V}, I_D = -2 \text{ A}, T_J = 125 ^{\circ}\text{C}$		425	541	
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = -10 \text{ V, } I_{D} = -2 \text{ A}$		5.4		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 75 V V 0 V		632	885	pF
Coss	Output Capacitance	$V_{DS} = -75 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		45	65	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1101112		1.3	2.0	pF
$R_g$	Gate Resistance		0.1	3	6	Ω

#### **Switching Characteristics**

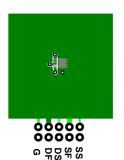
t <sub>d(on)</sub>	Turn-On Delay Time		8.5	17	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = -75 V, I <sub>D</sub> = -2 A,	2.2	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$	15	26	ns
t <sub>f</sub>	Fall Time		5.6	11	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0 V to -10 V	9.1	13	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ V to -6 V} V_{DD} = -75 \text{ V},$	5.6	7.9	nC
$Q_{gs}$	Gate to Source Charge	I <sub>D</sub> = -2 A	2.5		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		1.6		nC

#### **Drain-Source Diode Characteristics**

$V_{SD}$	Source-Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V, } I_{S} = -2 \text{ A}$ (Note 2)	-0.8	-1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = -2 A, di/dt = 100 A/μs	72	116	ns
Q <sub>rr</sub>	Reverse Recovery Charge		166	266	nC

Notes:

<sup>1.</sup>  $R_{0,\text{IA}}$  is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{0,\text{IC}}$  is guaranteed by design while  $R_{0,\text{CA}}$  is determined by the user's board design.



a) 53°C/W when mounted on a 1 in² pad of 2 oz copper



b) 125°C/W when mounted on a minimum pad

- 2. Pulse Test: Pulse Width < 300 $\mu$ s, Duty cycle < 2.0%.
- 3. Starting  $T_J$  = 25°C, L = 3 mH,  $I_{AS}$  = -5 A,  $V_{DD}$  = -150 V,  $V_{GS}$  = -10 V.
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

### **Typical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted.

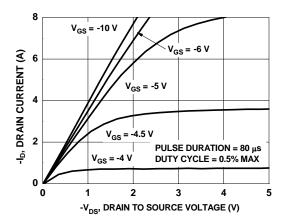


Figure 1. On Region Characteristics

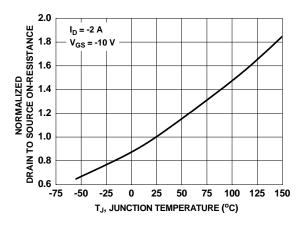


Figure 3. Normalized On Resistance vs. Junction Temperature

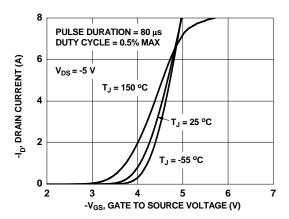


Figure 5. Transfer Characteristics

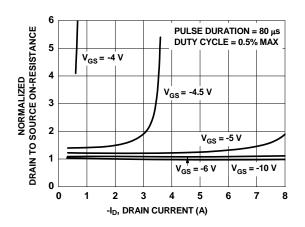


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

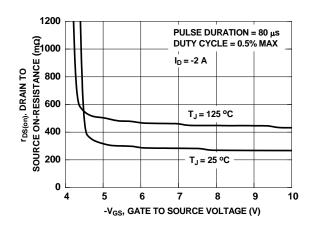


Figure 4. On-Resistance vs. Gate to Source Voltage

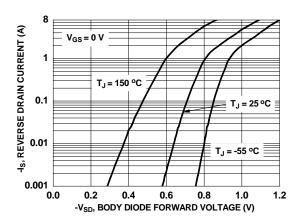


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

### **Typical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted.

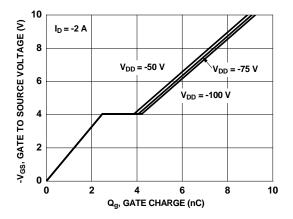


Figure 7. Gate Charge Characteristics

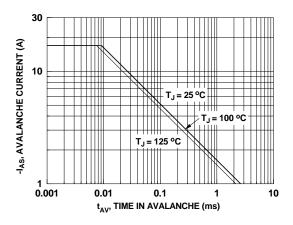


Figure 9. Unclamped Inductive Switching Capability

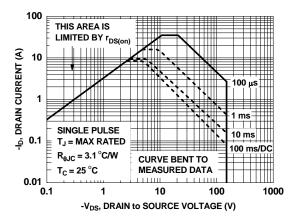


Figure 11. Forward Bias Safe Operating Area

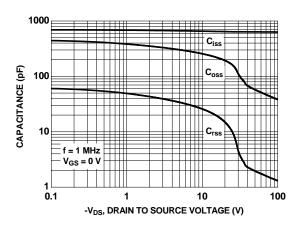


Figure 8. Capacitance vs. Drain to Source Voltage

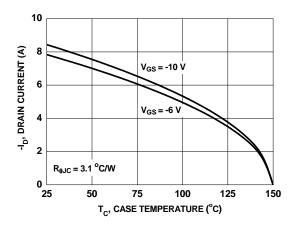


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

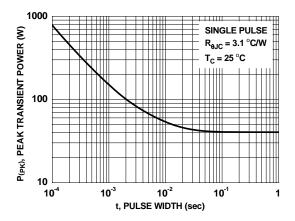


Figure 12. Single Pulse Maximum Power Dissipation

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

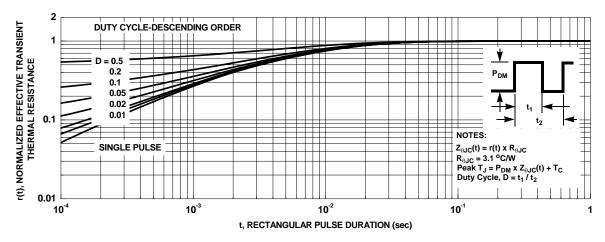
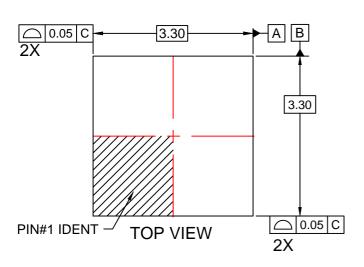
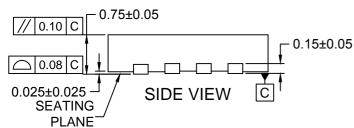
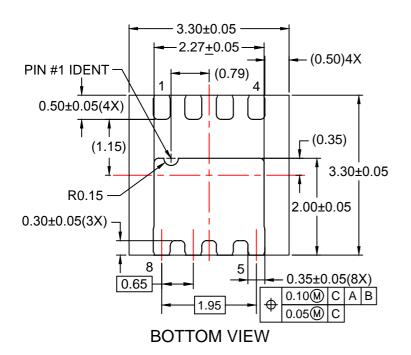
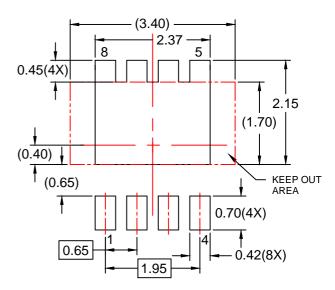


Figure 13. Junction-to-Case Transient Thermal Response Curve









RECOMMENDED LAND PATTERN

#### NOTES:

- A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP08Srev3.



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